



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: **10/829,115** Examiner: **Nitin Parekh**
Inventor: **Shyh-Ming Chang, Yuan-Chang Huang, Wen-Chih Chen
and Sheng-Shu Yang**
Filed: **April 20, 2004** Art Unit: **2811**
Title: **Bonding Structure With Compliant Bumps**

Certificate of Mailing

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Mail Stop Issue Fee, Formal Drawings, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the date shown below.

A handwritten signature in black ink, appearing to read "Jason Z. Lin".

Signature

A handwritten date in black ink, appearing to read "Sep. 26, 2005".

Date

SUBMISSION OF FORMAL DRAWINGS

Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450
Attn.: Official Draftsperson

Sir:

Enclosed are **twelve (12)** Replacement Sheets of the drawings for FIGs. 1-11 which have been approved by the Examiner for correcting informalities and filing in the above-identified U.S. patent application.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Jason Z. Lin".

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